

01-25-2005



DEPARTMENT OF COMMERCE
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RECORD A

P.

102925086

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Bong-Seok Suh
Ki-Chul Park
Seung-Man Choi
Il-Ryong Kim

Execution Date(s) December 23, 2004 & January 5, 2005

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: Samsung Electronics Co., Ltd

Internal Address: _____

Street Address: 416, Maetan-dong,

Yeongtong-gu

City: Suwon-si, Gyeonggi-do

State: _____

Country: Republic of Korea Zip: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

4. Application or patent number(s):

☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Anthony P. Onello, Jr.

Internal Address: _____

Street Address: Mills & Onello LLP

Eleven Beacon Street, 605

City: Boston

State: Massachusetts Zip: 02108

Phone Number: (617) 994-4900

Fax Number: (617) 742-7774

Email Address: mail@millsonello.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
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b. Deposit Account Number _____

Authorized User Name _____

9. Signature:

Anthony P. Onello, Jr.

Signature

January 11, 2005
Date

Anthony P. Onello, Jr., Registration No. 38,572

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 3

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Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

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PATENT
REEL: 016160 FRAME: 0106

A S S I G N M E N T

We, Bong-Seok Suh, of 101-1009, Hwanam Apt., 334-13, Yuljeon-dong, Jangan-gu, Suwon-si, Gyeonggi-do, Republic of Korea; Ki-Chul Park, of 425-702, Geonyeong 1 cha, Cheongmyeong Maeul 4danji Apt., Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea; Seung-Man Choi, of 111-104, Shinyeongtong Hyundai Apt., 865-1, Banwol-ri, Taean-eub, Hwaseong-si, Gyeonggi-do, Republic of Korea; and Il-Ryong Kim of 1295-3, Kwonseon-dong, Kwonseon-gu, Suwon-si, Gyeonggi-do, Republic of Korea, having invented improvements in METHOD OF FABRICATING SEMICONDUCTOR DEVICE BY FORMING DIFFUSION BARRIER LAYER SELECTIVELY AND SEMICONDUCTOR DEVICE FABRICATED THEREBY described in an application for Letters Patent of the United States, executed by us on even date herewith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

Reference No.: SAM-0675

First or Sole Inventor:

Signature: Bong-Seok Suh
Bong-Seok Suh

Date: Dec. 23, 2004

Second Joint Inventor:

Signature: Ki-Chul Park
Ki-Chul Park

Date: 1/5/2005

Third Joint Inventor:

Signature: Seung-Man Choi
Seung-Man Choi

Date: 1/5/2005

Fourth Joint Inventor:

Signature: Il-Ryong Kim
Il-Ryong Kim

Date: 12/23/2004

REFERENCE NO.: SAM-0675
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